CLAIM AMENDMENTS:

Claim 1 (Currently Amended): A bonding pad structure comprising:

a first pad for bonding; and

at least one second pad for probing, coupled with the first pad, wherein both of the first pad and the second pad are formed on an IC (Integrated Circuit) and remain in whole as part of the IC after fabrication.

Claim 2 (Original): The bonding pad structure according to claim 1, wherein the first pad is coupled with the second pad by a connecting wire.

Claim 3 (Previously Presented): The bonding pad structure according to claim 1, wherein the first pad is one of a plurality of first pads arranged according to a first pad layout on the IC, the second pad is one of a plurality of second pads arranged according to a second pad layout on the IC, and the second pad layout depends on an arrangement of testing probes for IC probing.

Claim 4 (Previously Presented): The bonding pad structure according to claim 3, wherein the first pad layout and the second pad layout are linear arrangements.

Claim 5 (Previously Presented): The bonding pad structure according to claim 3, wherein the first pad layout and the second pad layout are staggered arrangements.

Claim 6 (Previously Presented): The bonding pad structure according to claim 3, wherein the first pad layout is a staggered arrangement and the second pad layout is a linear arrangement.

Claim 7 (Original): The bonding pad structure according to claim 1, wherein the first pad comprises a bump ball.

Claim 8 (Previously Presented): The bonding pad structure according to claim 1, wherein the bonding pad structure is applied to a flip chip.

Claim 9 (Currently Amended): A bonding pad structure comprising:

a first pad for bonding; and

at least one second pad for probing, coupled with the first pad, wherein both of the first pad and the second pad are formed on a PCB (printed circuit board) and remain in whole as part of the PCB after fabrication.

Claim 10 (Previously Presented): The bonding pad structure according to claim 9, wherein the first pad is coupled with the second pad by a connecting wire.

Claim 11 (Previously Presented): The bonding pad structure according to claim 9, wherein the first pad is one of a plurality of first pads arranged according to a first pad layout on the PCB, the second pad is one of a plurality of second pads arranged according to a second pad layout on the PCB, and the second pad layout depends on an arrangement of testing probes for PCB probing.

Claim 12 (Previously Presented): The bonding pad structure according to claim 11, wherein the first pad layout and the second pad layout are linear arrangements.

Claim 13 (Previously Presented): The bonding pad structure according to claim 11, wherein the first pad layout and the second pad layout are staggered arrangements.

Claim 14 (Previously Presented): The bonding pad structure according to claim 11, wherein the first pad layout is a staggered arrangement and the second pad layout is a linear arrangement.

Claim 15 (Previously Presented): The bonding pad structure according to claim 9, wherein the first pad comprises a bump ball.